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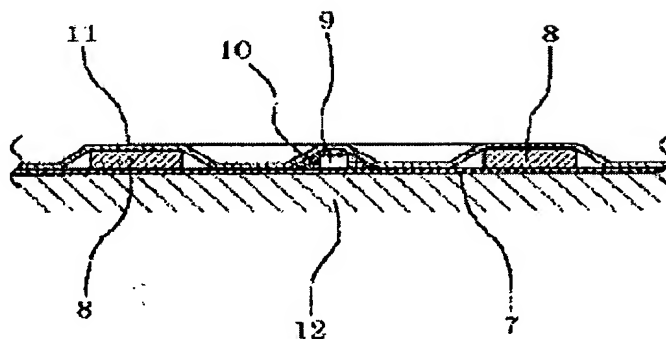
IC TAG

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View INPADOC patent family

Abstract of JP2001167240

PROBLEM TO BE SOLVED: To provide a structure capable of surely destroying an IC tag when the IC tag stuck once on an article is released. **SOLUTION:** This IC tag is provided with at least a doughnut coil-shaped copper wire being an antenna, a circuit part including an IC chip, a lead part derived from the doughnut coil-shaped copper wire and electrically connected to the circuit part, double-coated adhesive sheet provided with a release paper on the face on which a material to be stuck is stuck, and an insulating sheet. Then, the doughnut coil-shaped copper wire, in which the circuit part is arranged inside a doughnut, is placed on the double-coated adhesive sheet, and an adhesive is applied on the upper part around the circuit part thus the doughnut coil-shaped copper wire and the circuit part including the IC chip are held between the double-coated adhesive sheet and the insulating sheet.



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